

SPEC SHEET (FOR REFERENCE)	SHEET No.	Rev.	Page.
	G05063A	2	1 of 1

**TYPE:6PT2302P1A \* \***

CHIP SIZE	0.56 * 0.43mm
WAFER SIZE	6inch
POSSIBLE DIE PER WAFER	64,000pcs

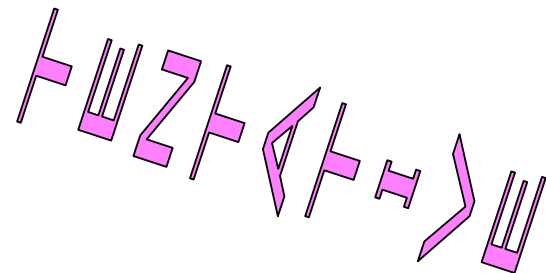
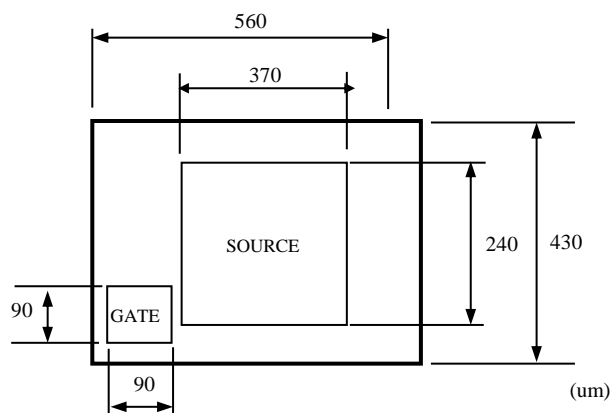
Maximum Ratings (Ta=25°C)

Characteristics	Symbol	Ratings	Unit
Drain-source voltage	VDSS	-20	V
Gate-source voltage	VGSS	±8	V

WAFER PROBING SPEC (Ta=25°C)

No	MODE	LIMIT			UNIT	CONDITIONS
		MIN.	Typ	MAX.		
1	IGSS1			±10	uA	VGS=±8V VDS=0V
2	IGSS2			±1	uA	VGS=±4.5V VDS=0V
7	IDSS			-500	nA	VDS=-20V VGS=0V
8	BVDSS	-23			V	ID=-250μA
9	VTH	-0.53		-1.2	V	ID=-250μA
10	RDS(on)1		0.25	0.36	Ω	VGS=-4.5V, ID=-350mA
11	RDS(on)2		0.37	0.55	Ω	VGS=-2.5V, ID=-300mA
12	RDS(on)3		0.55	1	Ω	VGS=-1.8V, ID=-150mA
13	VSD	-0.5		-1.1	V	I=-350mA VGS=0V
14	Yfs	200			mS	VDS=-10V Id=-200mA

※ Built-in ZD between Gate and Source.



NOTE: